Heat transport in turbulent Rayleigh-Benard convection: E ect of nite top-and bottom -plate conductivity

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(Dated: April 17, 2024)

Abstract

We describe three apparatus, known as the large, medium, and sm all apparatus, used for highprecision measurements of the Nusselt number N as a function of the Rayleigh number R for cylindrical samples of uid and present results illustrating the in uence of the nite conductivity of the top and bottom plates on the heat transport in the uid. We used water samples at a m ean tem perature of 40 C (P randtl number = 4:4). The sam ples in the large apparatus had a diameter D of 49.69 cm and heights L ' 116:33;74:42;50:61; and 16.52 cm . For the medium apparatus we had D = 24.81 cm, and L = 90.20 and 24.76 cm. The sm all apparatus contained a sample with D = 921 cm, and L = 952 cm. For each aspect ratio D =L the data covered a range of a little over a decade of R. The maximum R ' 1 10^{12} with Nusselt numbers N ' 600 was reached for = 0.43. Measurements were made with both A lum inum (conductivity $_{p} = 161$ W /m K) and Copper ($_{\rm p}$ = 391 W /m K) top and bottom plates of nom inally identical size and shape. For the large and medium apparatus the results with A lum inum plates fall below those obtained with Copper plates, thus con ming qualitatively the prediction by Verzicco that plates of nite conductivity diminish the heat transport in the uid. The Nusselt number N₁ for plates with in nite conductivity was estimated by tting simultaneously A lum inum - and Copper-plate data sets to an elective powerlaw for N₁ multiplied by a correction factor $f(X) = 1 \exp[(aX)^{b}]$ that depends on the ratio X of the therm al resistance of the uid to that of the plates as suggested by Verzicco. Within their uncertainties the parameters a and bwere independent of for the large apparatus and showed a sm all -dependence for the medium apparatus. The correction was larger for the large, sm aller for the medium, and negligible for the sm all apparatus.

I. IN TRODUCTION

The global heat transport by turbulent Rayleigh-Benard convection (RBC) in a uid heated from below usually is expressed in terms of the Nusselt number

$$N = Q L = T$$
(1)

where Q is the heat-current density, L the sample height, T the applied temperature dierence, and the therm alconductivity of the uid in the absence of convection. The dependence of N on the Rayleigh number

$$R = g T L^{3} =$$
 (2)

(is the isobaric therm alexpension coe cient, the therm aldi usivity, and the kinem atic viscosity) and the Prandtl number = is a central prediction of various theoretical models. [1, 2, 3, 4, 5, 6]

One of the experim ental problem s in the measurem ent of N (R) is that the side wall often carries a signi cant part of the heat current. [7, 8, 9, 10] It is di cult to correct for this e ect because the tem perature eld in the side wall is two-dimensional. Thus part of the applied current will pass from the wall near its bottom into the uid and from the uid near its top into the wall, thereby a exting the uid ow. This e ext can be minimized by using a uid of relatively large conductivity con ned by side walls of relatively low conductivity. Water con ned by Plexiglas or Lexan is a good choice from this point of view. How ever, a di erent experimental problem associated with uids of relatively large conductivity was pointed out recently by Chaum at et al, and by Verzicco. [11, 12] U sing direct num erical simulation, Verzicco showed that the top and bottom end plates of the convection sample, when they have a nite conductivity, diminish the heat transport in the uid. This e ect increases as the N usselt number grows with increasing R and, unless understood quantitatively, severely lim its the largest R at which quantitative estimates of the idealized N usselt number N $_1$ (R) in the presence of plates with in nite conductivity can be obtained. Verzicco found that, within his num erical resolution, the ratio f (X) of the measured N usselt number N to N $_1$ depends only on the ratio X (see Eqs. 4 to 6 below) of the e ective therm al resistance of the uid to the therm al resistance of the end plates. He derived an empirical form for f (X) from his simulation. However, the numerical work was done using certain idealizations that are not fully realized in a typical experiment, and it can not be expected that Verzicco's result for f(X), when used with experimental data for N, will yield quantitatively reliable results for N₁.

We used one old and built two new apparatus suitable for high-precision heat-transport measurements. The old one, to be called the small apparatus, was described before.[13] It contained samples of aspect ratio near one with a diameter near 9 cm. The other two, called the medium and large apparatus, will be described in detail in the next section. They were similar to each other in design, except that the large (medium) one accommodated samples of diameter D = 49:7 cm (D = 24:8 cm). We describe the large apparatus in detail in this paper. Except for the length of the side wall, the medium one used identical vertical dimensions, but had radial dimensions reduced appropriately.

Since the vertical structures of the end plates were nearly identical for the medium and large apparatus, we expected the same correction factor f(X) to apply for the medium and large apparatus. However, the measurements revealed that this is not the case. We made measurements for several aspect ratios D = L with two types of top and bottom plates of nominally identical shape and size. One set of plates was made of copper with a conductivity $_{Cu} = 391$ W/m K and the other of alum inum with $_{A1} = 161$ W/m K. The results indeed showed a lower elective N usselt number for the A lum inum plates, and for a given the difference increased with increasing Rayleigh number. As expected, our data were not quantitatively consistent with the function f(X) obtained by Verzicco. Thus we used the Copper- and A lum inum plate data at a given to derive an experimental correction function that, when applied to both data sets, caused all points to fall onto a single curve. In this analysis we retained Verzicco's conclusion that the correction can be expressed as a function of the ratio X of the thermal resistance of the uid to that of the end plates. For the large apparatus we found that the correction function is, within our resolution, independent of ; but for the medium apparatus the data yielded a small

-dependence. Contrary to our expectations f(X) was closer to unity at a given X for the medium apparatus than it was for the large one. This trend continued for the small apparatus, which yielded the same results within our resolution with copper and alum inum plates. For the medium and large apparatus we believe that the corrected results give the true N usselt number, unencum bered by side-wall or end-plate e ects, within a percent or so for R ayleigh numbers up to R ' 1 10¹². For the small apparatus a sidewall correction of

less than 2 percent was required.

Som e of our results for N_1 already have been published elsew here.[14, 15]

II. APPARATUS AND PERFORMANCE

A. Hardware

1. Large and Medium Apparatus

Here we describe in detail the large apparatus. For the medium one horizontal dimensions are reduced by approximately 24 cm, and vertical dimensions are the same. A schematic diagram is shown in Fig.1. From bottom to top, we nd rst a catchpan (A) capable of containing up to 200 liters of uid in case of a leak. Supported above it is a 81 cm diam eter support plate (B) made of high-strength alum inum alloy. It stands on three legs [solid lines between (A) and (B)] that consist of threaded 1.27 cm diameter steel rods screwed into tapped holes in part (B). The entire apparatus could be leveled by adjusting these legs. Part (C) was a bottom adiabatic shield made of alum inum. It was supported above part (B) by a 50 cm diameter steel cylinder [vertical lines between (B) and (C)] with a height of 7.6 cm and a wallthickness of 0.32 cm. The central area of 49.5 cm diameter of the bottom of (C) was covered uniform ly by parallel straight grooves of 0.76 cm depth and 0.40 cm width, interconnected by sem icircles at their ends. A djacent grooves were separated by 1.9 cm. Epoxied into the grooves was a heaterm ade of AW G No. 15 Nichrom e C resistance wire surrounded by berglas skewing. This heater had a total length of 10 m and a resistance of 6.8 .[16] A second auxiliary heater with a 7 resistance was wound around the outside of the shield.

Suspended above the shield, on a steel cylinder of 3.8 cm height and 0.32 cm wall thickness, was the bottom plate (D) of the sample. It was made in one case of high-strength alum inum alloy, and in the other of oxygen-free high-conductivity copper. It had a thickness of 3.5 cm. Its top surface was nely machined, with toolm arks of depth less than 3 m. W hen alum inum was used, the plate was coated by the \Tufiam " process [17]; the copper plate was uncoated. The bottom surface contained the same type of N ichrom e heater as the bottom shield. Its diam eter was 54.6 cm. A top central section had a reduced diam eter of 49.5 cm which was a close slide t into the plexiglas side wall cylinder (E). At one

point of the side of the section of reduced diam eter there was a vertical 0.16 cm diam eter sem i-circular groove through which the uid could enter the system. Five sm all holes were drilled from below at an angle into the bottom plate to within 0.32 cm of its top surface, and therm istors were mounted in these holes.

The inner diam eters D of the plexiglas side walls (E) were measured at several angular and axial positions, in several cases both before and after use. The standard deviation from the mean of the measurements for a particular side wall generally was 0.03 cm or less. For the large apparatus, where several side walls were used, the mean values of D were remarkably constant from one aspect ratio to another, and all fell in the range 49:68 < D < 49:70 cm. For the medium apparatus we had D = 24.81 cm. We saw no statistically signi cant evidence of changes due to the exposure to water during the experim ental runs. We estimate that system atic errors from uncertainties in the cross sectional area were less than 0.1%. The wall thickness was 0.63 cm for the large and 0.32 cm for the medium apparatus. The wall lengths L were uniform around the circum ference to 0.01 cm and determ ined the aspect ratio of the sam ple. Thus the uncertainty in the geom etry due to uncertainties in L also was less than 0.1%. In the present paper we report on m easurem ents for L = 116:33;74:42;50:61, and 16.52 cm, corresponding to = 0.427; 0.667; 0.981; and 3.008, for the large apparatus. For the medium one we used L = 90.20 cm and 24.76 cm, corresponding to = 0.275 and 1.00. We deliberately did not use an aspect ratio close to 1=2 in an e ort to avoid the multistability reported for this value on the basis of experiment [18] as well as of numerical simulations [19].

The side wall extended 2.38 cm below the top surface of the bottom plate. An ethylenepropylene O -ring sealed the system from the outside well below the top surface of the bottom plate. A similar construction was used to term inate the side wall at the top. This construction m inimizes the heat ow into the wall and provides a well de ned geometry for simulations of this heat- ow problem. [7]

The side wallwas surrounded by an adiabatic side shield (F) made of alum inum . Epoxied to the outside of this shield was a double spiral consisting of 15 m of alum inum tubing. W ater from a temperature-controlled circulator owed through the tubing. The shield was suspended above the support plate (B) by six 1.9 cm diam eter and 17.5 cm long plastic rods (not shown in Fig. 1). During measurements its temperature was kept close to the mean temperature of the system.

The top of the sample was provided by an alum inum or copper top plate (H) which was sin ilar to the bottom plate in its dimensions. The alum inum plate was also \Tufram " plated. The top plate contained an outlet for the uid which was identical to the inlet in the bottom plate, but in the sample assembly care was taken to locate the outlet at an angular position opposite to the inlet. The top plate di ered from the bottom one in that it did not contain a heater. Instead, it was cooled by tem perature controlled water from a refrigerated circulator.[20] It had a thickness of 3.34 cm, and a double-spiral water-cooling channel was m achined directly into it. The channel width and depth were 0.95 - 2.54 cm². The spacing between adjacent turns of the spiral was 2.54 cm. [21] The bottom of the groove came within 0.79 cm of the metal-uid interface. An additional plate was \0 "-ring sealed to the top plate from above to close the spiral channel. Sm all holes were drilled through the two-plate composite from above to within 0.32 cm of the alum inum - uid interface, and calibrated therm istors were mounted with their heads within 0.48 cm of the convecting uid. Each them istor was protected from circulating water by an additional small \0 "-ring between the two plates. To avoid convection of air in the vicinity of the sample, the entire space outside the sample but inside the dashed rectangle K was led with low-density (m ness rating 1) polyurethane foam sheet.

The large apparatus was intended also for future work with compressed gases as the uid. Thus, a retaining plate (I) and tension rods (G) were provided to sustain the force exerted by pressures up to 10 bar. They were not in use during the measurements reported here.

The medium and large apparatus each contained 16 therm istors [22] that were calibrated simultaneously in a separate apparatus against a laboratory standard based on a standard platinum therm on eter. D eviations of the data from the twere generally less than 0.002 C. In the top as well as the bottom plate one therm istor term inated at the plate center and four were located equally spaced on a circle of 43 cm diam eter. The remaining therm istors were mounted on the adiabatic bottom shield, the adiabatic side shield, and the outside of the plate is side wall. The power of the bottom -plate heater was determ ined by a four-lead m ethod.

The sample was leveled to better than 0.1. In order to look for any in uence of a m isalignment relative to gravity, a few data points were taken also with the sample tilted by 2. No significant election N was noted.

2. SmallApparatus

The small apparatus had been used extensively for the study of pattern form ation near the onset of RBC, and was described in detail in Ref. [13]. The top plate was cooled from above by circulating tem perature-controlled water. The bottom plate was heated by a m etal-

In heater from below. The apparatus was used for the work reported in Refs. [7, 23, 24], and there it contained a sample of acetone at a mean temperature of 32.00 C (= 3.97). A recent new set of measurements was made as well with this con guration. The sample had a 0.318 cm thick sapphire top plate and a 0.635 cm thick A lum inum bottom plate. [7, 23, 24] The transparent sapphire had the advantage of giving optical access. It had the disadvantage that therm om eters could not be mounted within it and that the top tem perature had to be determ ined with a therm on eter in mersed in the cooling bath. A small correction for the series resistance of the sapphire and of a boundary layer above the sapphire in the water bath was then required. [25] H igh-density polyethylene side walls compatible with acetone, were used. They had a relatively high conductivity and the uid had a relatively small conductivity. Thus a signi cant wall correction, ranging from about 15% at small to about 8% at large R, was required [7] and introduced an uncertainty of several percent for the nal corrected data. In recent m easurem ents the sapphire top and alum inum bottom plates were replaced with 0.635 cm thick Copper plates with therm om eters mounted directly in them, within 0.3 cm of the metal-uid interface. Corrections for the tem perature di erences between the therm on eters and the metal-uid interfaces were then quite small. As shown in the Appendix, the results dem onstrate that no Verzicco correction is required for the runs with the sapphire top and alum inum bottom plates.

New measurements were made also in a di erent con guration, using water at 40 C as the uid. Here top and bottom alum inum or copper plates of identical dimensions were used. The plates were 1.90 cm thick. Of this thickness, 0.63 cm protruded as an anvil into a 9.21 cm diameter Lexan side wall. The side wallwas 0'-ring scaled to the plates at a point beyond the metal- uid interface, well away from the bulk uid. The side wallhad a thickness of 0.32 cm . Only a sm all wall correction was required. First, a correction was made for the conductance of the system with an evacuated sample cell. This correction was dom inated by a contribution due to the conductance from the bottom plate directly to a surrounding water bath.[13] B ased on model 2 of R ef. [7] we estim ate that the actual non-linear correction for the wall conduction was about 1.7% at R ' $3 \ 10^7$ where N ' 24 to 0.8% for R ' 10^9 where N ' 66. We found that the results with copper and alum inum plates agreed with each other within their uncertainty, indicating that the Verzicco correction was not required in the Rayleigh-num ber range and for the geometry of this apparatus. We believe that the wall-corrected results are subject to system atic errors of less than one percent.

B. Procedure and Perform ance

This section is based on experience with the large apparatus. The performance of the medium one was similar.

The measurements were made using de-ionized water. The water was degassed by circulating it with a peristaltic pump for one or two days through a small stirred container external to the sample at about 50 C. A fler this procedure, visual inspection of the sample showed complete absence of any bubbles. All data points are for a mean temperature close to 40 C where the Prandtl number is 4.38. The variation of over the applied tem – perature di erence can be estimated from $(1=)(d=dT) = 0.020K^{-1}$. At 40 C water has the following properties: density = 992.2 kg/m⁻³, isobaric therm al expansion coe cient = 3.88 10⁻⁴ K⁻¹, therm al conductivity = 0.630 W /m K, heat capacity per unit mass at constant pressure C_P = 4170 J/kg K, therm all di usivity = 1.528 10⁻⁷ m²/s, and kinematic viscosity = 6.69 10⁻⁷ m²/s.

The system was equilibrated with both top and bottom plates at 40 C for over a day. Thereafter the power needed to maintain the bottom plate tem perature was constant and equal to 0.2 W. We do not know the origin of this parasitic heat loss, but subtracted it from all subsequent measurements. It was about 0.8% (0.04%) of Q for T = 1(10) C.A possible dependence of this correction on the tem perature of the bottom plate constitutes one of the possible sources of error for the measurements with small T.

We determ ined the conductance between the bottom plate and the bottom adiabatic shield by changing the shield temperature with the bottom plate at 40 C, and found it to be about one W / C. Thus, the regulation of the shield temperature within better than 0.01 C of the bottom plate temperature reduced heat exchange between the shield and the bottom plate to a negligible value.

W em easured the in uence of the adiabatic side-shield tem perature T_s on the heat current

necessary to maintain a constant temperature di erence across the sample. We found this current to decrease by 1.3 W when T_s was increased by 1 C. The side shield was always kept within about 0.1 C of the mean sample temperature, and thus heat exchange with it was not a signi cant source of error except perhaps at the smallest values of T where the heat current through the sample was small.

In the remainder of this section we describe the performance of the system for ' 1. Similar behavior was found for other values.

D ata points were obtained by holding constant both the top and bottom plate tem perature. For the bottom plate this was done by adjusting the heater power in a digital feedback loop using the central therm on eter (T_0) . For the top plate a constant tem perature was achieved by circulating tem perature-controlled water [20] through the double spiral. The heat current applied to the bottom plate and all ve therm on eters in each plate were monitored for a minimum of 8 hours, frequently for one day, and on occasion for ten days under nom inally constant external conditions. U sually a constant current and constant tem peratures were obtained after less than an hour. This is illustrated in Fig. 2, where we show the apparent Nusselt number computed from the top-and bottom -plate tem peratures and the heat current during the transient after a change of the Rayleigh number from about 10^{10} . One sees that the transients had a relaxation time $_{\rm N}\,$ of about 300 10^{10} to 8:4 1 sec, and died out within our resolution after only about half an hour. The relaxation time was about the same for the Rayleigh number (i.e. for T), and we believe it to be controlled by the rate at which we can provide/rem ove the energy necessary to heat/cool the bottom /top plate rather than by hydrodynam ic transients. Nonetheless it is instructive to com pare the observed relaxation time with an estimate of an internal time constant of the system. It is signi cantly faster than a simple relaxation process involving the entire system and an elective vertical therm aldi usion time $_{\rm N}$ = $\rm L^2=(~^2N$) $^\prime$ 600s. This suggests that the relatively thin boundary layers adjacent to the top and bottom plates equilibrate quite quickly, and that the large-scale circulation is also established on a relatively short time scale. Our experience indicates that the concerns expressed by Roche et al. [18] about very long tim e constants for N usselt-num ber m easurem ents using water are unwarranted, at least for the aspect ratios that we exam ined.

The currents and tem peratures recorded after the st several hours were time averaged. The ve averaged tem peratures for each plate were averaged to give our best estimate of

the top and bottom plate temperatures. A correction to these temperatures was made for the temperature change across the alum inum or copper layers between the uid and the therm istor heads. For the alum inum plates this correction was estimated to be 0.8% (1.5%) of T for T = 1(10) C; for the copper plates it was smaller by a factor of 2.4. The results for T_t and T_b yielded the nalvalues of T = $(T_b + T_t)=2$, and of the value of T = T_b T_t use to compute N.

Recently it was appreciated that the heat ux from (to) the bottom (top) plate occurs preferentially near the circum ference of the plate, with smaller uxes near the center. [26] This will inevitably lead to horizontal therm algradients in plates of nite conductivity. To our know ledge no system atic measurements of such gradients have been made for actual experimental conditions. In Figs. 3 and 4 we show the horizontal temperature di erences T_i T_0 , i = 1;2;3;4 between therm on eters 1 to 4 near the plate periphery and therm on eter 0 at the plate center, norm alized by the applied vertical temperature di erence T. Here Fig. 3 is for the A lum inum and Fig. 4 is for the Copper plates. In both cases (T_i T_0) = T is at most of the order of a few percent. Surprisingly, the results for Copper (which has 2.5 times the conductivity of A lum inum) are not very di erent in magnitude from the A lum inum data. We note that in detail the results will depend on the nature and orientation of the large-scale circulation which prevails in the sam ple. For the determ ination of the N usselt num bers we used the average of all the therm on eters in a given plate. We would estim ate that this horizontal inhom ogeneity of the tem perature at the uid boundary could introduce a system atic error of order 1 percent into the results for N.

III. EFFECT OF THE TOP-AND BOTTOM -PLATE CONDUCTIVITIES

A. Experim ental evidence

In Fig. 5 we show the = 1 results (large apparatus) for alum inum (copper) plates as open squares (circles) on double logarithm ic scales. Corresponding data were obtained in the large apparatus for = 3:00, 0.67, and 0.43, in the medium apparatus for = 0:275 and 1.00, and in the sm all apparatus for = 0:967. A loo show n, as open triangles, are the data for acetone (with P randtl number = 4:0) from Ref. [23]. The acetone data were corrected for the wall conduction using m odel 2 of Ref. [7] (see also Ref. [24]). Their range of R only barely overlaps with that of the present data, but there is consistency. The solid line is the prediction of the model by G rossm ann and Lohse (GL). This model had been tted to data that included the acetone results, and thus it to the acetone data quite well. The new data with alum inum plates depart from the prediction more and more as R increases. The results with copper plates agree well with the GL prediction. However, as we shall see below, to some extent this agreement is illusory because the agreement will be spoiled somewhat by a correction for the nite conductivity of the copper plates. In Sect. IIIB we show that the di erence between the experimental results obtained with copper and alum inum plates can be understood in terms of the nite plate-conductivity as proposed by Verzicco. [12]

B. Verzicco Correction

Recently it was shown by Verzicco [12], by including the top and bottom plates in direct num erical integrations of the Boussinesq equations, that a nite conductivity of the top and/orbottom plates of a sam ple will dim inish the heat transport by the uid. The physical reason for this phenom enon is found in the signi cance of \plum es" for the heat transport. Much of the therm all energy that leaves the more or less quiescent boundary layer above the bottom plate does so in the form of modestly sized relatively warm and thus buoyant uid volum es that have become known as plum es. These plum es leave behind an enthalpy de ciency that takes the form of a \cold spot" in the bottom plate. This cold spot, if it has a nite lifetime, decreases the likelihood of further plum e form ation, and thus decreases the heat ux out of the bottom boundary layer. An analogous process occurs at the cold top plate.

Verzicco carried out extensive num erical simulations for a system of aspect ratio = 1=2, with identical top and bottom plates and isotherm alboundary conditions on the dry sides of the plates. For that case he showed that the e ect of the plate conductivity on the measured N usselt num ber can be described in term s of a function f (X), with

$$N = f(X)N_1 :$$
 (3)

where N_1 is the ideal N usselt number in the presence of perfectly conducting rigid top and bottom plates. The argument X is the ratio of the thermal resistance of the uid to that of

an end plate, i.e.

$$X = R_{f} = R_{p}$$
(4)

$$= X_0 = N$$
; (5)

$$X_0 \qquad {}_{p}L=(fe) \tag{6}$$

with R_f and R_p equal to the resistances of the uid and of a plate respectively. Here $_p$ and $_f$ are the end-plate and uid conductivities respectively, and e is the thickness of one plate. Several of the conditions used in the simulations do not correspond to the experiment. The actual bottom plate is closer to experiencing a constant heat ux, the top plate is cooled in its interior by water channels, and the plate geom etries are significantly different at the top and bottom . Further, the experiments are not for the same as the simulations. Thus we do not expect the Verzicco prediction to be quantitatively applicable; but the difference between the results with copper and alum inum plates shown in Fig. 5 is in the predicted direction and of about the right size. Thus the measurements provide qualitative con is mation of the importance of the Verzicco e ect.

At large R the dependence of N on R can be written approximately as $N = N_0 R^{1=3}$. We note that in this approximation X is given by

$$X = \frac{{}^{p} ()^{1=3}}{{}_{f} e N_{0} (g)^{1=3}} T^{1=3}$$
(7)

and is independent of the height and diam eter of the sam ple. Thus, regardless of the aspect ratio and the overall dimensions, the correction is predicted to be nearly the same for the same T. Approximately, it should depend only on a constant combination of sample cell and uid properties, and on T¹⁼³. As we shall discuss below, we not this not to be the case. The correction for the large apparatus is significantly larger than it is for the medium one even though the top and bottom plates have the sam e vertical dimensions. For the small apparatus (which did have a dimension end-plate structure) no correction was needed.

From his num erical results Verzicco derived the emperical form ula

$$f(X) = f_V(X) = f1 \exp[((X=4)^{1=3})gX = (X = 2)$$
 (8)

for the case where the Nusselt number is determined from the temperatures at the uid-plate interfaces (as is the case in the experiment). In Fig. 7 we show this function as a dashed line.

C . Results for the large apparatus

To obtain an estimate of the size of the correction, we evaluated X as a function of R for four aspect ratios using an average e' 1:9 cm of the thickness of the bottom plate and of the part of the top plate below the water cooling channels. U sing this and the measured N usselt numbers, we obtained the values shown in Fig. 6 as solid and dashed lines for copper and alum inum respectively for the large apparatus. C learly the copper plates, having much larger values of X, should yield results much closer to N₁ than the alum inum plates.

In Fig.8a we present experimental results for N. We use the \compensated" form N = R^{0:3} in order to obtain su cient resolution in the graph. We compare the uncorrected results for N (open symbols) for = 3:00 (left data set), = 1:00 (m iddle data set) and = 0:67 (right data set) with the estimates of N₁ based on Eq.8 and the values of X given in Fig. 6 (solid symbols). One sees that the functional form Eq.8 does not lead to a collapse of the data obtained with the copper and alum inum plates, indicating as expected that the Verzicco function f_V is not quantitatively applicable to the data.

In order to obtain a better estimate of N $_1$, we replaced $f_{\rm V}$ (X) with the slightly dimension emperical function

$$f(X) = 1 \exp[(aX)^{D}]$$
: (9)

On the basis of the physical process envisioned by Verzicco (see Sect. IIIB) we feel that the form of Eq.9 is a better choice for two reasons. First it is a monotonically increasing function of X, which it should be since we expect the correction to become smaller as X becomes larger (N becomes smaller, see Eq. 5). This is so because we expect fewer plum es to be emitted for smaller N. Second, f(X) is less than unity for all values of its argument which it should be because the physical process envisioned can not enhance the heat transport by the uid. We note that f_V has a minimum at small X and is greater than unity both for smalland large X (of course we understand that it was meant to be used only over a limited range of X where it was monotonically increasing and less than unity).

We simultaneously the alum inum - and copper-plate data for a given to the equation

$$N = N_0 R^{eff} f(X); \qquad (10)$$

i.e. over the experimental range of R for a given (about one decade) we represented N_1 by an elective powerlaw with an elective exponent $_{eff}$. The parameters N_0 , $_{eff}$,

a, and b were least-squares adjusted. The results are listed in Table I. Typical statistical errors for both a and b were near 0.02, but system atic errors due to sm all uncertainties in the sam ple diam eter and height m ade a sim ilar contribution to their uncertainties. Thus, within experimental error we found that f(X) is independent of . We adopted the values a = 0.275 and b = 0.39 for all . The corresponding f(X) is shown as a solid line in Fig.7. We repeated the least-squares ts, adjusting N₀ and eff. The resulting parameter values are again given in Table I. Corresponding results for N and N₁ based on the copper- and alum inum -plate data are shown in Fig.8b. One sees that the results for N₁ (solid symbols) for alum inum (squares) and copper (circles) plates within their scatter collapse onto a single curve.

D. Results for the medium apparatus

Estimates of X for the medium apparatus are shown in Fig 6 as dash-dotted and dotted lines for copper and alum inum plates respectively. They are seen to be comparable in size to those for the large apparatus. Results of measured values of $N = R^{0.3}$ for = 1.00 and 0.275 are shown in Fig. 9 as open symbols, with the squares (circles) obtained with alum inum (copper) plates. Again there is a difference that can be attributed to the difference in the plate conductivity; but this difference is smaller than it was in the case of the large apparatus. A gain a t of Eq. 9 to the data yielded values of N_1 (solid symbols) that agreed for the two types of plates. The coefficients obtained from the ts are given in Table I. They difference shown in Fig. 7 as dash-dotted lines. These lines lie well above the solid one, rejuding the fact that the correction for the medium apparatus is much smaller than it is for the large apparatus.

${\tt E}$. Results for the sm all apparatus

Results of measured values of $N = R^{0.3}$ for = 0.967 obtained with the small apparatus using water at 40 C as the uid are shown in Fig. 10 as open symbols, with the squares (circles) obtained with alum inum (copper) plates. In this case we see that there is no signi cant in uence of the plate conductivity on the results. Thus either set of data should

be a good representation of N $_1$.

IV. SUMMARY AND CONCLUSION

In this paper we described a large, a medium, and a small apparatus for the measurement of heat transport in turbulent Rayleigh-Benard convection. Over the range 10^8 10^{12} R we studied the in uence of the nite conductivity of the top and bottom con ning plates by making measurements in each apparatus for samples with various aspect ratios. In each case we used two sets of plates of nom inally identical geometry, one made of copper with relatively high conductivity and the other m ade of alum inum with lower conductivity. As predicted by Verzicco, [12] we found for the large and medium apparatus that the Nusselt num ber was dim inished m ore when the plate conductivity was smaller, and that this e ect could be represented by an empirical correction factor f (X) that is a function of the ratio X of the therm al resistance of the plates to that of the uid (Eq.3). For the large apparatus we found that f (X) is, within our resolution, independent of the aspect ratio of the sam ple (see Eq. 9 and Table I); for the medium apparatus there was a small aspect-ratio dependence. A lthough both the medium and large apparatus required a plate correction to obtain the conductivity N₁ for plates of in nite conductivity, we found that this correction was smaller for the medium apparatus. For the small apparatus the data indicate that no correction is required.

O ne aspect of this phenom enon is worth noting. In the R-range of interest N is approximately proportional to R¹⁼³. In this approximation one can show (see Eq. 7) that, at constant plate thickness e, the argument X of f (X) is proportional to T¹⁼³ and independent of the sample size and aspect ratio. Thus, to a good approximation the correction for the nite plate-conductivity is expected to be equally important for measurements at relatively small N and R, provided that the sample height is relatively small so that the applied temperature difference T is large. This is illustrated above by the data in Fig. 8 for various (and thus L) but with the same diam eter D and plate thickness e.

From the measurements for the large and medium sample we found that a change of the overall size of the sample (i.e. of L and D in proportion to each other) at constant and e changes the correction f(X) considerably even though the argument X is about the same. The dependence of f(X) on the physical size of the apparatus seems surprising. At this

point we can only speculate about a possible reason. One explanation might be found by considering again the limit where (at constant T) N R $^{1=3}$ L (see Eq. 2) and where (see the previous paragraph) X is independent of L . In that lim it we consider the size $l_{\mathbb{P}}$ of a \plum e" that created a therm al \hole" of lateral extent 1 in, say, the bottom plate. We expect $\frac{1}{2}$ to be of the same order as the therm alboundary-layer thickness 1' L=2N [1], which (at constant T) yields $l_{\rm P}$ independent of L. Finally, we consider the time P = 1 = v needed by the large-scale circulation (LSC) of speed v to traverse the therm all hole. If this time is long compared to the therm al relaxation time of the hole in the bottom plate (which should depend only on the plate properties), then the e ect of a previously generated plume on further plume emission should be small. For v we have v / $R_e = L$ where R_e is the Reynolds number of the LSC. To a good approximation one expects [1, 4] $R_e = R^{4=9} = L^{4=3}$, and thus $P = L^{1=3}$. We conclude that indeed p is larger for a shorter cell, thus suggesting a diminished Verzicco e ect. This argument could be a ected by an R dependence of the plum e density above (below) the bottom (top) plate; little is known about this from experiment, but a recently proposed model [27] suggests that this density is independent of R.

A nother unexpected result is the noticeable, albeit small, -dependence of f(X) for the medium sample. Here we note that the LSC structure for the two aspect ratios most likely is very dierent. For '1 we expect a single role lling the entire cell. For '0.28 it is likely that two or more rolls positioned vertically above each other prevail. One would expect such a dierence in the LSC geometry to in uence the speed v of the LSC above (below) the bottom (top) plates, leading to somewhat dierent sizes of the Verzicco e ect.

The work presented here enables us to make reliable estimates of the theoretically relevant N usselt number N₁ of a system with in nite thermal conductivity of the top and bottom boundaries. Some of the results for N₁ have already been published elsewhere, [14, 15] and we shall discuss the implications of the results for N₁ in further detail in a future publication. Here we just note that N₁ di ers signi cantly from the predictions of the G rossm ann-Lohse model [5] with the model parameters currently in use. This can be seen in Fig. 8 where the model prediction is shown as a solid line. It will have to be determined whether the model parameters can be adjusted so as to re-gain satisfactory agreement.

A second point to be noted is that the data in Figs. 8 and 9 allow at most a very sm all dependence of N $_1$ on the aspect ratio . We appreciate that this observation di ers from

prior m easurem ents [23, 28] of N that were not corrected for the wall e ect [7, 8, 9, 10] or the Verzicco end-plate e ect discussed in the present paper.

Finally, in an Appendix we re-exam ine previously published data and present new measurements with acetone as the uid. We conclude that the older results had not been in uenced signi cantly by the nite plate-conductivity e ect.

V. ACKNOW LEDGMENT

This work was supported by the US D epartment of Energy through G rant DE-FG 02-03ER 46080.

VI. APPENDIX

P revious measurements, for a P randtlnum ber close to four, were reported in Refs. [23], [7], and [24] where acetone with = 3.96 was used. Those data covered the range 10^8 R 10^{10} and were corrected for the in uence of the side wall on the heat ux, [7] but not for the e ect of the end plates on the turbulent ow (which had not been anticipated at that time). Here we consider brie y the end-plate e ect.

The sam ple cell had an inside diam eter of 8.74 cm and a side wall of high-density polyethylene (HDPE) of thickness 0.38 cm. However, the top and bottom of the side wall each had a HDPE ange of thickness 0.73 cm (including the side-wall thickness) and heigh 0.47 cm adjacent to the uid, thus making any estimate of the nonlinear side-wall correction [7] quite uncertain. The sam ple cell consisted, from bottom to top, of an alum inum bottom plate of thickness $e_{A1} = 0.635$ cm (conductivity $_{A1} = 161$ W/m K), a sam ple of acetone of height L = 8:70 cm ($_{f1} = 0.159$ W/m K), a sapphire top plate of thickness $e_{sapp} = 0.317$ cm ($_{sapp} = 37$ W/m K), and a circulating water cooling bath. The bottom -plate tem perature was measured by them istors in bedded in it about 0.2 cm from the uid-solid interface; a correction for the tem perature drop between the therm istors and the uid was negligible. The tem perature at the top was measured in the water coling bath. The tem perature di erences were corrected for the tem perature drop across the sapphire (which ranged from 1 percent near R = 10^8 to 3 percent near R = 10^{10}), and for the tem perature drop due to an estimated therm al resistance R_b ' 0:009 K/W of a boundary layer in the water bath above the sapphire (which ranged from 0.4 percent near $R = 10^8$ to 1.3 percent near $R = 10^{10}$). [25] A correction of 0.085 W /K (22 percent near $R = 10^8$ and 6.5 percent near $R = 10^{10}$) was measured with an evacuated sample cell and used to correct the heat current, but for present purposes no further (non-linear) correction for the side-walle ect [7] was made. The results for the reduced N usselt number are shown in Fig. 11 as open circles.

To con m the above results we made a new set of measurements after the sample had been taken apart and then assembled again four years later, and obtained results represented by the open squares in Fig. 11, in good agreement with the previous data.

O nem ight attempt to correct for the top- and bottom-plate in uence using Eqs. 3 and Eq. 9 with the coe cients given in Table I. The nature and geometry of the boundaries in the acetone experiments were very dierent from those of the copper and alum inum plates used in the present work, and there is no reason why the results Eqs. 3 and Eq. 9 with the coe cients in Table I should apply quantitatively. Nonetheless it is instructive to exam ine the size of the predicted e ect. We estimated an average plate resistivity $R_p = (e_{sapp} = _{sapp} + e_{Al} = _{Al}) = 2 = 0.62 \text{ cm}^2 \text{K}/\text{W}$ and computed X from Eqs. 4 to 6. This model then predicts a modest correction to N (4 percent near R = 10^{10}) at the largest R.

To obtain an experimental estimate of the plate ell, we constructed a new sample cell. The same HDPE side wall was used. The top and bottom plates were replaced by copper plates of dimensions equal to those of the previous aluminum and sapphire plates. In this case the top-plate temperature was measured with a thermistor in bedded in the top plate, thus eliminating any series resistance in the water bath. An estimate similar to that of the previous paragraph predicts that any plate correction should be completely negligible. The results for N are shown in reduced form in Fig. 11 as solid circles. They agree well with the measurements with the aluminum bottom and sapphire top plate. Thus we conclude that the end-plate correction for the original acetone experiment was negligible.

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TABLE I: Param eters obtained from ts of Eqs. 9 and 10 to the data with alum inum and copper top and bottom plates. Entries marked with a indicate xed values.

	D (am)		а	b	N ₀	eff
	49.7	0.43	0.240	0.434	0.06401	0.3303
	49.7	0 . 67	0.250	0.428	0.0684	0.3281
	49.7	1.00	0.288	0.361	0.0733	0.3261
	49.7	3.00	0.279	0.392	0.0902	0.3164
	49.7	0.43	0.275	0.39	0.06395	0.3306
	49.7	0 . 67	0.275	0.39	0.0680	0.3287
	49.7	1.00	0.275	0.39	0.0744	0.3251
_	49.7	3.00	0.275	0.39	0.0897	0.3167
	24.8	0.275	0.304	0.506	0.0838	0.3194
	24.8	1.00	0.378	0.488	0.1047	0.3101

FIG.1: Schematic diagram (not to scale) of the large apparatus. The various parts are explained in the text.

FIG. 2: The e ective Nusselt number as a function of time after a sudden change of the top and bottom plate temperatures.

FIG.3: The horizontal tem perature di erences $(T_i \quad T_0) = T$ for the alum inum top (a) and bottom (b) plates and = 1. Here T is the vertical applied tem perature di erence, and i = 1;2;3;4labels the peripheral therm on eters in counterclockwise sequence when viewed from above. Open circles: i = 1, solid circles: i = 2; open squares: i = 3; solid squares: i = 4.

FIG. 4: The horizontal tem perature di erences $(T_i \quad T_0) = T$ for the copper top (a) and bottom (b) plates and = 1. The symbols are as in Fig. 3.

FIG.5: The Nusselt number as a function of the Rayeigh number for = 1.0 on logarithm ic scales. Open triangles: Data for acetone from Ref. [23] after correction for the wall conduction. Open squares: Results from the large apparatus with alum inum top and bottom plates. Open circles: Results from the large apparatus with copper top and bottom plates. Solid line: the prediction of Ref. [5].

FIG. 6: The ratio X of the therm all resistance of the unid to the average resistance of the top and bottom plate as a function of the Rayleigh number R. Solid lines: large sample, copper plates. Dashed lines: large sample, alum inum plates. From left to right, those lines are for = 3, 1,0.67, and 0.43. Dash-dotted lines: medium sample, copper plates. Dotted lines: medium sample, alum inum plates. From left to right, those lines are for = 1 and 0.275. The lines cover the range of R used in the experiments. FIG. 7: Results for the correction factor $f = N = N_1$. Dashed line: $f_V(X)$ derived from direct num erical simulations in Ref. [12]. Solid line: f(X) (see Eq. 9) with a = 0.275 and b = 0.39 derived from the present experiments with the large apparatus. Dash-dotted lines: f(X) (see Eq. 9) derived from the present experiments with the medium apparatus (upper curve: = 1.00, lower curve: = 0.28).

FIG.8: The compensated Nusselt number $N = R^{0.3}$ for the D = 49.7 cm diameter sample on a linear scale as a function of the Rayeigh number R on a logarithm ic scale. Open symbols: measured values of N. Solid symbols: estimates of N₁ obtained by correcting for the elect of the top and bottom plates on the heat transport in the uid. Circles: copper top and bottom plates. Squares: alum inum top and bottom plates. In (a) the form ula suggested in Ref. [12] (Eq. 8, dashed line in Fig. 7) was used. In (b) Eq. 9 with a = 0.275 and b = 0.39 (solid line in Fig. 7) was used. From left to right, the data sets are for = 3.0; 1.0, and 0.43. For comparison we show the prediction of Ref. [5] based on a to the data from Ref. [24] as solid lines.

FIG. 9: The compensated Nusselt number $N = R^{0.3}$ for the D = 24.8 cm diameter sample on a linear scale as a function of the Rayeigh number R on a logarithm is scale. From left to right, the two data sets are for = 1.00 and 0.275. Open symbols: measured values of N. Solid symbols: estimates of N₁ obtained by correcting for the e ect of the top and bottom plates on the heat transport in the uid. Circles: copper top and bottom plates. Squares: alum inum top and bottom plates. Equation 9 with a = 0.378 (0:304) and b = 0.488 (0:506) (dash-dotted lines in Fig. 7) was used for = 1.00 (0:275).

FIG.10: The measured (i.e. uncorrected) compensated Nusselt numbers $N = R^{0.3}$ for the D = 9.21 cm diameter sample (= 0.967) on a linear scale as a function of the Rayeigh number R on a logarithm ic scale. Circles: copper top and bottom plates. Squares: alum inum top and bottom plates.

FIG.11: Reduced Nusselt numbers $N = R^{0:3}$ obtained in the small apparatus with acetone at 32 C for = 1:00.0 pen circles: data from Ref. [7] with an alum inum bottom and a sapphire top plate (the data were re-analyzed with small changes of the series resistance and di er slightly from those originally reported). Open squares: new data obtained with an alum inum bottom and a sapphire top plate. Solid circles: new data obtained with copper top and bottom plates. The conduction of the empty sample cell was subtracted, but no further correction for the e ect of the side walls on the heat current was made. The small vertical bar represents one percent.



Fig.1



Fig.2



Fig.3



Fig.4



Fig.5



Fig.6



Fig.7



Fig.8



Fig.9



Fig. 10



Fig. 11